Thermal stabilities and dynamic mechanical properties of dielectric materials for next generation PCB

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Abstract: Recently, high performance microelectronic devices are designed in multi-layer structure in order to make dense wiring of metal conductors in compact size. For making dense wiring of metal conductors, we investigated CTE and peel strength of dielectric materials for next generation PCB. It is an object of this research to develop an epoxy resin composition for an interlayer insulating material exhibiting low CTE and high peel strength and making an insulating layer thinner.